

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Xiao-Chun Mu et al.

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

Docket No.: 884.798US1

Serial No.: 09/733,289

Filed: December 8, 2000

Due Date: N/A

Examiner: DiLinh Nguyen

Group Art Unit: 2814

**MS Amendment**

Commissioner for Patents

P.O. Box 1450

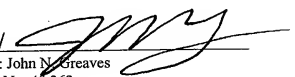
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ Communication Concerning Related Applications (1 pg.).
- ☒ Supplemental Information Disclosure Statement (3 pgs.), Form 1449 (1 pg.), and copies of 3 cited documents.

SCHWEGMAN, LUNDBERG & WOESSNER, P.A.

Customer Number 21186

By:   
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 25<sup>th</sup> day of February, 2008.

JUDY DENT

Name

  
Signature

SCHWEGMAN, LUNDBERG & WOESSNER, P.A.

(GENERAL)